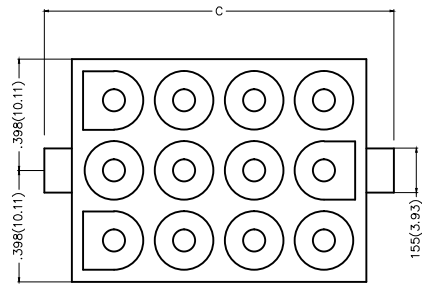
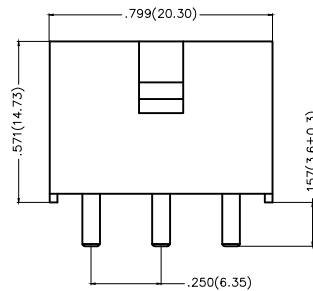
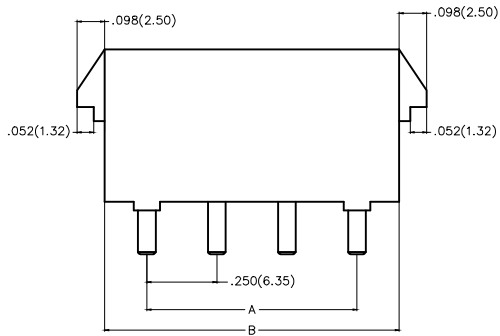


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



**Electrical**  
 Current Rating: 10A AC(rms)/DC  
 Voltage Rating: 600V AC(rms)/DC  
 Contact Resistance: 10 mΩ Max  
 Insulation Resistance: 1000 MΩ MIN  
 Withstanding Voltage: 5000V AC r.m.s  
 Temperature Range—Operating: -25°C ~ +85°C  
**Material and Plating**  
 Housing: PA66( UL 94V-0)  
 Contact Pin: Brass  
 Plating: Tin Plated

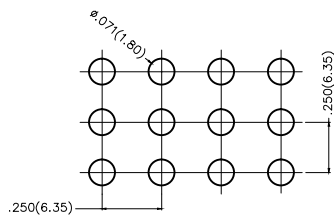
Material and Plating : Housing PA66 UL94V-0 , Tin-Plated.				
Circuits (n)	Part No.	Dimensions(in/mm)		
		A	B	C
9	FWF63503-T09S22TB	.500(12.70)	.799(20.30)	.996(25.30)
12	FWF63503-T12S22TB	.750(19.05)	1.051(26.70)	1.248(31.70)
15	FWF63503-T15S22TB	.100(25.40)	1.299(33.00)	1.496(38.00)



### Ordering Information

FWF 635 03 — T XX S 2 2 T B  
 1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 635—Pitch 6.35mm	3	Distinction No. 03	4	Row Option Triple Row	5	Circuits XX	6	Entry Angle S—180° Vertical
7	Plating 2—Tin Plated	8	Material—Resin 2—PA66	9	Color—Resin T—Transparent	10	Packaging B—PE Bag				



Recommended P.C.Board Layout

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF63503-TXXS22TB	ITEM NO. FWF63503	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5°	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 6.35mm 180° Vertical (DIP)		REV 0
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX'±1°	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		